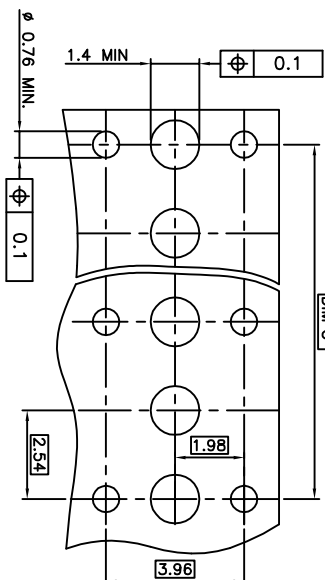
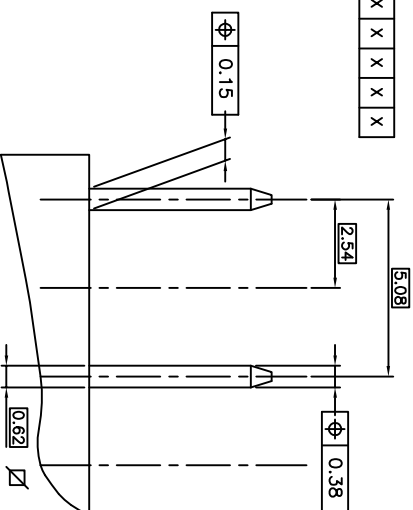


RECOMMENDED HOLES PATTERN

RECOMMENDED PC BOARD THICKNESS: 1.6 mm



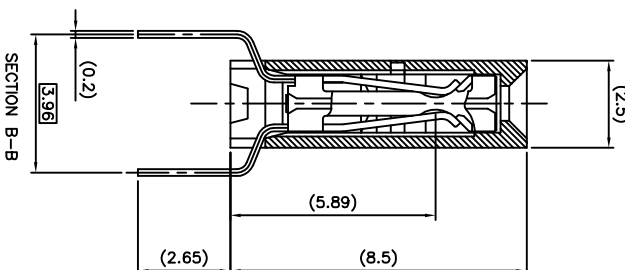
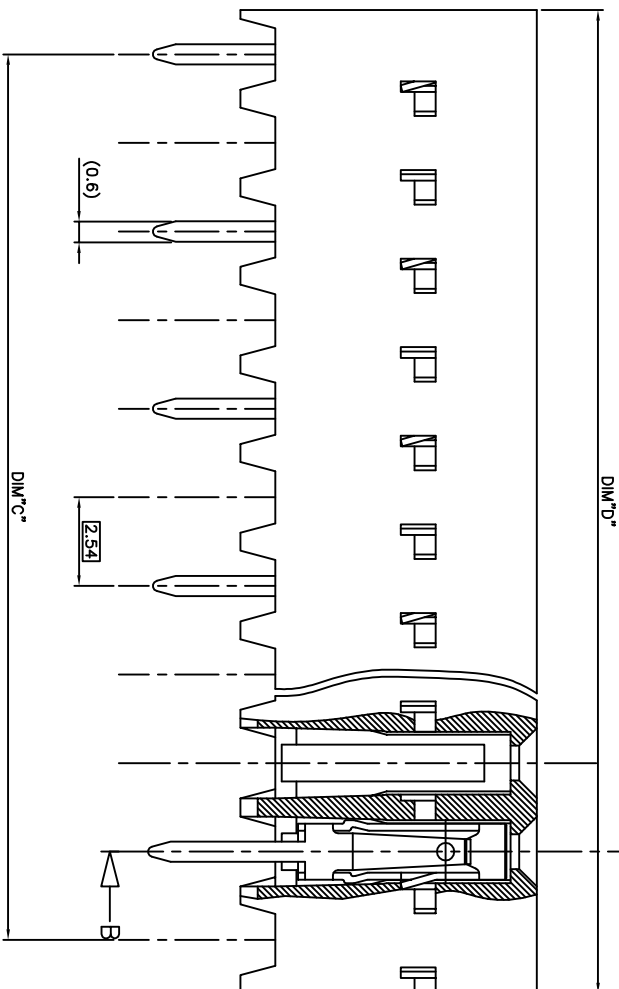
				CONTACT PLACED IN CAVITY (TABLE ACCORDING VIEW A)																														
PRODUCT N°	HOUSING	DIM"C"	DIM"D"	NB. OF TER.																														
					1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28		
95234-Y01LF	1 X 28 pos.	68,58	71,04	14	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
95234-Y02LF	1 X 13 pos.	30,48	32,94	10	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
95234-Y03LF	1 X 3 pos.	5,08	7,54	2	X	X	X																											
95234-Y04LF	1 X 7 pos.	15,24	17,70	4	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
95234-Y05LF	1 X 4 pos.	7,62	10,08	2	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
95234-Y06LF	1 X 14 pos.	33,02	35,48	10	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X		
					5,08																													

RoHS COMPATIBLE.
SEE NOTE 4

RECOMMENDED PINS PATTERN

NOTES:

- 1 - MATERIAL HOUSING: THERMOPLASTIC POLYESTER 70% GLASS FILLED, COLOR BLUE, FLAME RETARDANT PER UL-94 CATEGORY VO.
- 2 - MATERIAL TERMINAL: PHOSPHOR BRONZE EXTRA HARD.
- 3 - CONNECTOR TO BE USED ON PC BOARD WITH NON PLATED THROUGH HOLES
- 4 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS
- a - PLATING:
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 24um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.
- b - MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- c - LABELING:
- MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT: SEE GS-47-0004



SECTION B-B

95234-4XXLF	5 µm Sn	Sn
95234-3XXLF	0.76 µm GOLD	Sn
PLATING CODE	CONTACT AREA	SOLDER TAIL
	PLATING THICKNESS OVER 1.27µm NI	